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(71) Applicant (for all designated States except US): **3M INNOVATIVE PROPERTIES COMPANY** [US/US]; 3M Center, Post Office Box 33427, St. Paul, MN 55133-3427 (US).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **JOSEPH, William, D.** [US/US]; 3m Center, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

(74) Agent: **GWIN, Sanders, H., Jr.**; Shumaker & Sieffert, P.A., 1625 Radio Dr. Suite 300, Woodbury, MN 55125 (US).

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(54) Title: POLISHING PAD WITH FLOATING ELEMENTS AND METHOD OF MAKING AND USING THE SAME

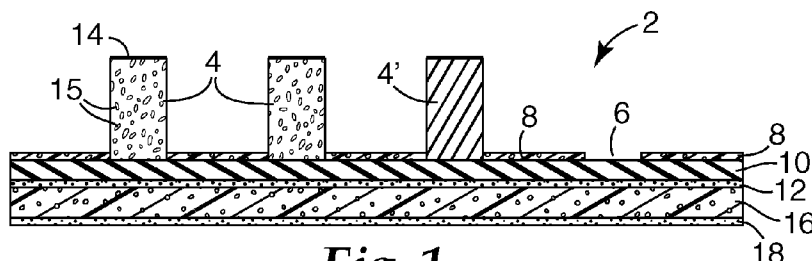


Fig. 1

(57) Abstract: The disclosure is directed to polishing pads with floating polishing elements bonded to a support layer, for example by thermal bonding, and to methods of making and using such pads in a polishing process. In one exemplary embodiment, the polishing pad includes a multiplicity of polishing elements, at least some of which may be porous, each polishing element affixed to a major surface of a support layer so as to restrict lateral movement of the polishing elements with respect to one or more of the other polishing elements, but remaining moveable in an axis substantially normal to the support layer. In certain embodiments, the polishing pad may additionally include a compliant layer affixed to the support layer opposite the polishing elements, and optionally, a polishing composition distribution layer. In some embodiments using porous polishing elements, the pores are distributed substantially at a polishing surface of the polishing elements.